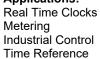
IL3T Series

Product Feature:

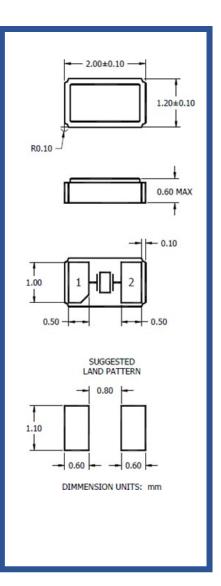
Low Cost SMD Package Pb Free/ RoSH Compliant Ultra-Low Profile

Applications:



	-
Frequency	32.768 kHz
	90 kΩ Maximum
Equivalent Series Resistance (ESR)	(-40°C to +85°C Option)
	110 kΩ Maximum
	(-40°C to +125°C Option)
Shunt Capacitance (Co)	0.9 ~ 1.2pF Typical
Frequency Tolerance @ 25°C ±5°C	±20 ppm (See Options)
Frequency Stability over	Parabolic, -0.03 ppm / ° C ²
Temperature	± 0.01 ppm / ° C ²
Turnover point	+25° ±5°C
Mode of Operation	Flexural Mode (Tuning Fork)
Crystal Cut	Tuning Fork
Load Capacitance	12.5pF (See Options)
Drive Level	0.1 μW Typical, 0.5 μW Maximum
Aging (@25°C± 3°C)	±2 ppm Max. / First Year
Q Value	90000 Min
Operating Temperature Range	-40° C to +85° C (See Options)
Storage Temperature Range	-55° C to +125° C
Insulation Resistance	500 Mohms Minimum
	(at 100Vdc +/-15Vdc)



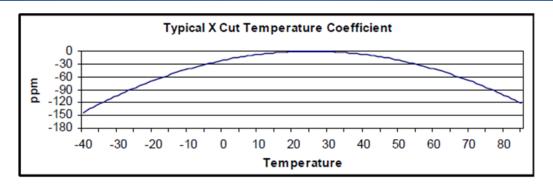


Part Num	Part Number Guide Sample Part Number: IL3T – HX5F12.5- 32.768kHz					
Package	Stability(ppm) at Room Temperature	Stability (ppm) over Operating Temperature	Operating Temperature	Mode (overtone)	Load Capacitance (pF)	Frequency
IL3T -	J = ±10ppm H = ±20ppm	X = X Cut	5 = -40°C to +85°C	F = Fundamental	4= 4pF 6 = 6pF 7 = 7pF	-32.768 kHz
	F = ±30ppm		6 = -40°C to +125°C		9 = 9pF 12.5 = 12.5pF (or Specify)	

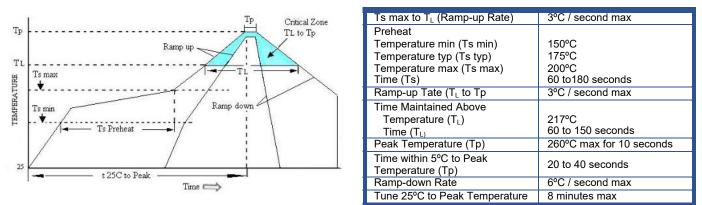
IL3T Series



Typical X Cut Temperature Coefficient:



Pb Free Solder Reflow Profile:



Units are backward compatible with 240°C reflow processes

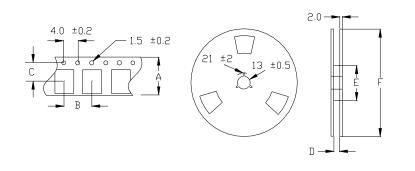
Package Information:

MSL = 1

Termination = e1 (Sn/Cu/Ag over Ni over Kovar base metal)

Note: Due to material availability, the outline and finish color of the component may vary. This variation in no way affects the electrical performance of the product.

Tape and Reel Information:



Quantity per Reel	3000
A	8.0 ±0.2
В	4.0 ±0.1
C	3.5 ±0.05
D	9±0.3
E	60 / 80
F	180 / 250

Dimensions: mm

IL3T Series



Environmental Specifications:

Thermal Shock	MIL-STD-883, Method 1011, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A
Resistance to Soldering Heat	J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max)
Hazardous Substance	Pb-Free / RoHS Compliant
Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Terminal Strength	MIL-STD-883, Method 2004, Test Condition D
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2, R1=2x10-8 atm cc/s
Solvent Resistance	MIL-STD-202, Method 215